

# **Thyristor Surge Suppressors (TSS) Data Sheet**

## **Description**

DO-214AA Thyristor solid state protection thyristor protect telecommunications equipment such as modems, line cards, fax machines, and other CPE.

P Series devices are used to enable equipment to meet various regulatory requirements including GR 1089, ITU K.20, K.21 and K.45, IEC 60950, UL 60950, and TIA-968 (formerly known as FCC Part 68).



#### **Features**

Compared to surge suppression using other technologies, P Series devices offer absolute surge protection regardless of the surge current available and the rate of applied voltage (dv/dt). P Series devices:

- Cannot be damaged by voltage
- Eliminate hysteresis and heat dissipation typically found with clamping devices
- Eliminate voltage overshoot caused by fast-rising transients
- Are non-degenerative
- Will not fatigue
- Have low capacitance, making them ideal for high-speed transmission equipment
- Meets MSL level 1, per J-STD-020

#### **Electrical Parameters**

Parameter	Definition					
V <sub>DRM</sub>	Peak Off-state Voltage – maximum voltage that can be applied while maintaining off state					
Vs	Switching Voltage – maximum voltage prior to switching to on state					
V <sub>T</sub>	On-state Voltage – maximum voltage measured at rated on-state current					
I <sub>DRM</sub>	Leakage Current – maximum peak off-state current measured at V <sub>DRM</sub>					
Is	Switching Current – maximum current required to switch to on state					
I <sub>T</sub>	On-state Current – maximum rated continuous on-state current					
I <sub>H</sub>	Holding Current – typical current required to maintain on state					
Со	Off-state Capacitance – typical capacitance measured in off state					
Ірр	Peak Pulse Current – maximum rated peak impulse current					





### **Electrical Characteristics**

Part Number	V <sub>DRM</sub> (V)	Vs (V)	V <sub>T</sub> (V)	I <sub>DRM</sub> (μΑ)	I <sub>S</sub> (mA)	I <sub>T</sub> (A)	I <sub>H</sub> (mA)	C <sub>O</sub> (pF)	I <sub>PP</sub> 10/1000μs (A)	V <sub>PP</sub> 10/700μs (V)	Marking Code
P2300SD	190	260	4	5	800	2.2	50	100	200	8000	P23D

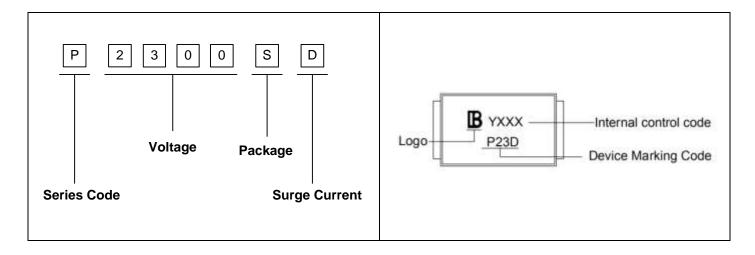
#### Notes:

- All measurements are made at an ambient temperature of 25°C. IPP applies to -40°C through +85°C temperature range.
- Off-state capacitance(Co) is measured at 1 MHz with a 2V bias and is typical value.

### **Thermal Considerations**

Package DO-214AA/SMB Symbo		Parameter	Value	Unit
	TJ	Operating Junction Temperature	-40 to +125	°C
	Ts	Storage Temperature Range	-40 to +150	$^{\circ}\!\mathbb{C}$
	R <sub>θJA</sub>	Junction to Ambient on printed circuit	90	°C/W

## **Part Number Code and Marking**







### **Characteristics Curves**

Figure 1. V-I Characteristics

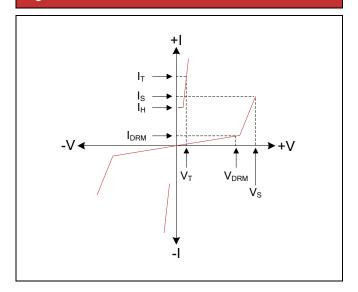


Figure 3. Normalized Vs Change versus Junction Temperature

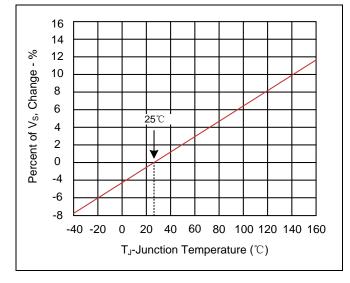


Figure 2. tr x td Pulse Wave-form

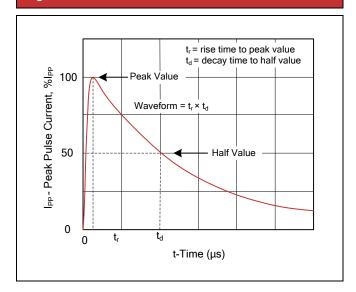
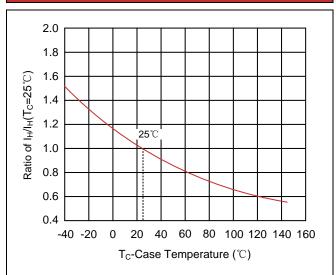
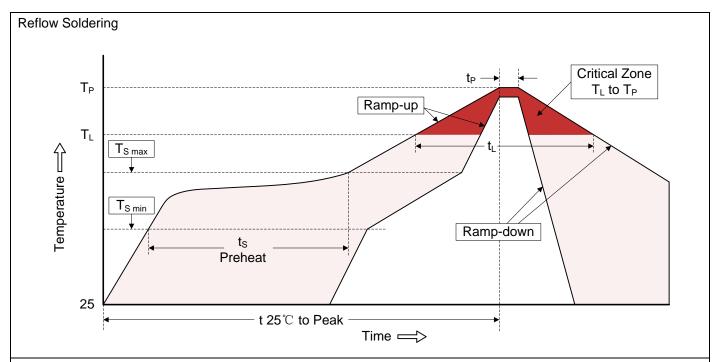


Figure 4. Normalized DC Holding Current versus
Case Temperature





# **Recommended Soldering Conditions**



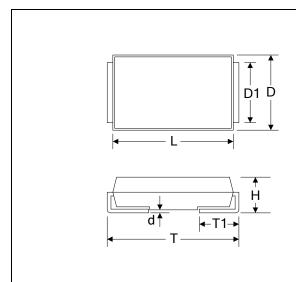
### **Recommended Conditions**

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T <sub>L</sub> to T <sub>P</sub> )	3°C/second max.
Preheat -Temperature Min (T <sub>S min</sub> ) -Temperature Max (T <sub>S max</sub> ) -Time (min to max) ( t <sub>S</sub> )	150°C 200°C 60-180 seconds
T <sub>S max</sub> to T <sub>L</sub> -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature (T <sub>L</sub> ) -Time (t <sub>L</sub> )	217°C 60-150 seconds
Peak Temperature (T <sub>P</sub> )	260℃
Time within 5°C of actual Peak Temperature (t <sub>P</sub> )	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.





# **Dimensions (SMB/DO-214AA)**



Symbol	Millim	neters	Inches		
	Min.	Max.	Min.	Max.	
L	4.06	4.70	0.160	0.185	
D	3.30	3.94	0.130	0.155	
D1	1.90	2.20	0.075	0.086	
Т	5.21	5.59	0.205	0.220	
T1	0.76	1.52	0.030	0.060	
d	-	0.203	-	0.008	
Н	1.95	2.65	0.077	0.104	

## **Packaging**

